

SHENMAO Features LED Die Bonding Solder Pastes at IPC APEX 2016

SHENMAO proudly announces a series of **Lead-free LED Die Bonding Solder Pastes** made locally in the USA and with the same quality in 8 other worldwide locations for various Die Bonding processes. Powder Size is available from T3 to T8.

SHENMAO PF606-P116 offers Long Stencil Printing Life, High Tackiness (slump resistant), and consistent printability with Superior Wetting Characteristics for LED Die Bonding Highly Reliable and Lowest Void (Smaller and Fewer Voids) Solder Joints with Optimum Maximized Quality through Highest Productivity.

SHENMAO PF606-P128 LED Die Bonding Solder Paste, available for dispensing in Syringes in Lower Viscosity, exhibits excellent Slump Characteristics, consistent dispense ability, and stable tackiness.

SHENMAO PF606-XP LED Dipping Solder Paste has great Viscosity Characteristics and stable Tackiness exhibiting extremely uniform Dipping Volume and Transfer Rate for consistent High Quality Solder Joints.

As the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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